

Description

HDPE 56020 S XP is a very high molecular weight (VHMW) high density polyethylene (HDPE) with high resistance to impact, good chemical resistance and optimized balance between Environmental Stress Cracking Resistance (ESCR) and rigidity. It has been specifically designed for the manufacture of blow molded UN-marked articles (tight head drums, open top drums and jerry-cans) dedicated for the transportation of dangerous goods. HDPE 56020 S XP is a pellet grade and contains antioxidants.

Characteristics

| Property | Method | Unit | Typical value (*) |
|--|--------------|-------------------|-----------------------|
| Density | ISO 1183 | g/cm ³ | 0.952 |
| Melt Flow Rate (190°C/21.6 kg) | ISO 1133/G | g/10 min | 1.4 |
| ESCR Antarox 100% | ASTM D 1693B | h | F ₅₀ > 250 |
| Notched Charpy Impact Resistance 23°C | ISO 179-1 | kJ/m ² | 80 |
| Notched Charpy Impact Resistance -30°C | ISO 179-1 | kJ/m ² | 55 |

(*) Data not intended for specification purposes

Processing

It is recommended to process HDPE 56020 S XP within the temperature range 180-230°C.

Handling and storage

Please refer to the safety data sheet (SDS) for handling and storage information. It is advisable to convert the product within one year after delivery provided storage conditions are used as given in the SDS of our product. SDS may be obtained from the website:

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